



Statement of Materials, Construction

80L LQFP TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.30900	Cu	7440-50-8	0.38080	0.56206	95.17
				Fe	7439-89-6	0.00081	0.00119	0.20
				Zn	7440-32-6	0.00404	0.00596	0.18
				Pb	7439-92-1	0.00020	0.00030	0.05
				Ni	7440-02-0	0.01292	0.01906	3.20
				Mn	7439-96-5	0.00040	0.00060	0.10
				Si	7440-21-3	0.00293	0.00432	0.73
				Silver (plating)	7440-22-4	0.00081	0.00119	0.20
				Mg	7439-95-4	0.00071	0.00104	0.18
2	Die	Silicon Chip	0.01000	Si	7440-21-3	0.01194	0.01762	99.50
3	Die Attach Material	Conductive Epoxy	0.00300	Epoxy Resin	Proprietary	0.00035	0.00051	15.00
				Silver	7440-22-4	0.00183	0.00270	79.50
				Aromatic Amine	Proprietary	0.00013	0.00019	5.50
4	Wire	Gold	0.00125	Au	7440-57-5	0.00040	0.00059	99.99
5	Lead Finish	Alloy	0.04025	Pb	7439-92-1	0.00402	0.59407	10.00
				Sn	7440-31-5	0.03622	5.34661	90.00
				Fused Silica	60676-86-0	0.15188	0.22418	81.70
6	Encapsulation	Epoxy Resin	0.31400	Brominated Epoxy Resin	68541-56-0	0.00279	0.00412	1.50
				Carbon Black	1333-86-4	0.00056	0.00082	0.30
				Epoxy resin	Proprietary	0.01394	0.02058	7.50
				Phenol Resin	Proprietary	0.01394	0.02058	7.50
				Antimony Trioxide	1309-64-4	0.00279	0.00412	1.50
Total Package Weight			0.67750					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%